



## Final Product Change Notification

202106030F01 : MC33771B Product Burn-In Elimination On Improved Quality Robustness Silicon Design

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Jul 09, 2021 **Effective date:** Oct 07, 2021

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### Management summary

Burn-in Elimination from the Final Test production flow for the BCC14 Rev B+ MC33771B products.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input checked="" type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

## PCN Overview

### Description

NXP Semiconductors announces the Burn-in elimination from the Final Test production flow for the MC33771B Battery Cell Controller IC products associated with this notification. As previously informed with notification 202008032IU01 (Sep 2020), MC33771B product was migrated to an improved quality robustness design. The burn-in process was originally introduced on MC33771B product to address qualification rejects linked to PMV5 capacitors. The PMV5 capacitors were removed from MC33771B with the enhanced quality design migration.

In order to confirm efficiency of the new design, NXP performed a burn-in study. The burn-in elimination evaluation was successfully completed after testing 100k units from 5 different wafer lots and 12 assembly lots, processed in the same wafer fabrication facility, with zero burn-in related failures.

Upon PCN 202106030F01 approval, the burn-in process will be removed from the Final Test production flow for improved quality design MC33771B products.

Please see the attached files for additional details.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-QG-01

#### **Reason**

The original reason for burn-in implementation (qualification rejects linked to PMV5 capacitors), has been resolved with product migration to improved quality design.

Burn-in elimination can now proceed, and results in optimized manufacturing test flow for reduced cycle time and enhanced product delivery.

#### **Identification of Affected Products**

Product identification does not change

#### **Product Availability**

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#### **Sample Information**

Not Applicable

#### **Production**

Planned first shipment Oct 07, 2021

#### **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

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No Impact on form, fit, function, reliability or quality

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

#### **Timing and Logistics**

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Aug 08, 2021.

#### **Related Notification**

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<b>Notification</b>	<b>Issue Date</b>	<b>Effective Date</b>	<b>Title</b>
202008032IU01	Sep 20, 2020	Sep 21, 2020	MC33771B Design Quality Robustness Improvement Update Notification

#### **Contact and Support**

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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<b><u>Changed Orderable Part#</u></b>	<b><u>12NC</u></b>
SC33771BTP1MAE	935382539557
MC33771BTB2AER2	935349656528
MC33771BTB2AE	935349656557
MC33771BSP2AER2	935349658528
MC33771BSP2AE	935349658557
MC33771BSP1AER2	935349661528
MC33771BSP1AE	935349661557
MC33771BSA1AER2	935349742528
MC33771BSA1AE	935349742557
MC33771BTA2AER2	935350619528
MC33771BTA2AE	935350619557
MC33771BTP2AER2	935350622528
MC33771BTP2AE	935350622557
MC33771BSB2AER2	935350624528
MC33771BSB2AE	935350624557
MC33771BSA2AER2	935350994528
MC33771BSA2AE	935350994557
MC33771BSB1AER2	935350996528
MC33771BSB1AE	935350996557
SC33771BTA1MAER2	935373626528
SC33771BTA1MAE	935373626557
SC33771BTP1MAER2	935382539528